

FY2019

Financial Announcement

(Financial supplement material)

May 14, 2019

V-Technology Co.,Ltd.

President: Shigeto Sugimoto

Forward-Looking Statements

This material contains forward-looking statements regarding V Technology Co., Ltd.'s corporate plans, strategies, forecasts, and other statements that are not historical facts. They are based on current expectations, estimates, forecasts and projections about the industries in which V Technology Co., Ltd. operates.

As the expectations, estimates, forecasts and projections are subject to a number of risks, uncertainties and assumptions, including without limitation, changes in economic conditions; fluctuations in currency exchange rates; changes in the competitive environment; the outcome of pending and future litigation; and the continued availability of financing and financial instruments and financial resources, they may cause actual results to differ materially from those presented in such forward-looking statements.

V Technology Co., Ltd., therefore, wishes to caution that readers should not place undue reliance on forward-looking statements, and, further that V Technology Co., Ltd. undertakes no obligation to update any forward-looking statements as a result of new information, future events or other developments.



Financial Result

Highlight of FY2019 Q4

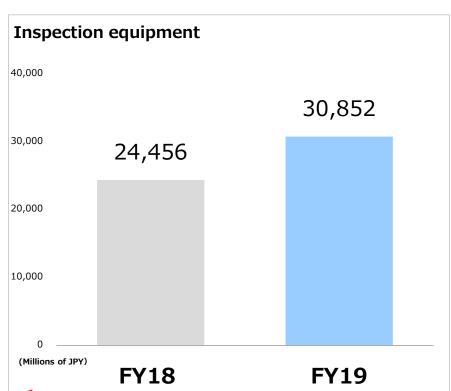
- Both sales and profits have reached record highs for four consecutive terms.
- Although sales decreased due to delivery delays for some reasons attributable to customers, and cost reduction also the unaccrued expenses such as R & D and M & A resulted in the expected profit.
- Orders dropped 56.6% to 47.4 billion yen due to a break in large FPD related investment.
- The order backlog recovered in Q4, but fell 21.4% to 90.9 billion yen.

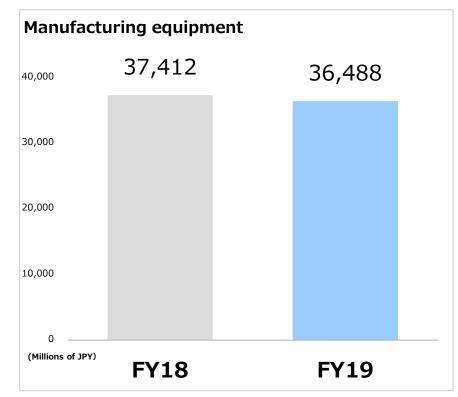
	FY18 Year ended		FY19 Year ended		Y/Y
	Amount (Millions of JPY)	Margin	Amount (Millions of JPY)	Margin	change
Net sales	66,067	100.0%	72,132	100.0%	9.2%
Gross profit	21,321	32.3%	25,144	34.9%	17.9%
Operating profit	12,545	19.0%	16,628	23.1%	32.5%
Ordinary profit	12,370	18.7%	16,767	23.2%	35.5%
Net profit attributable to owners of parent	7,837	11.9%	10,901	15.1%	39.1%
Orders received	109,323	1	47,430	1	-56.6%
Backlog	115,637	_	90,935	_	-21.4%



*Reference: Sales by Products

- Manufacturing equipment
 - Sales of large-size FPD equipment remained steady.
 - CF exposure equipment continues to secure close to 100% market share.
- Inspection equipment
 - Sales of inspection equipment for large FPDs and OLEDs is solid. Sales of TP measuring machines and OS testers continue to grow steadily and it secures 80 to 90% market share.
 - Sales of correction equipment increased by about 70% from last year. In particular, we reached 80% market share in the correction device for TFT.

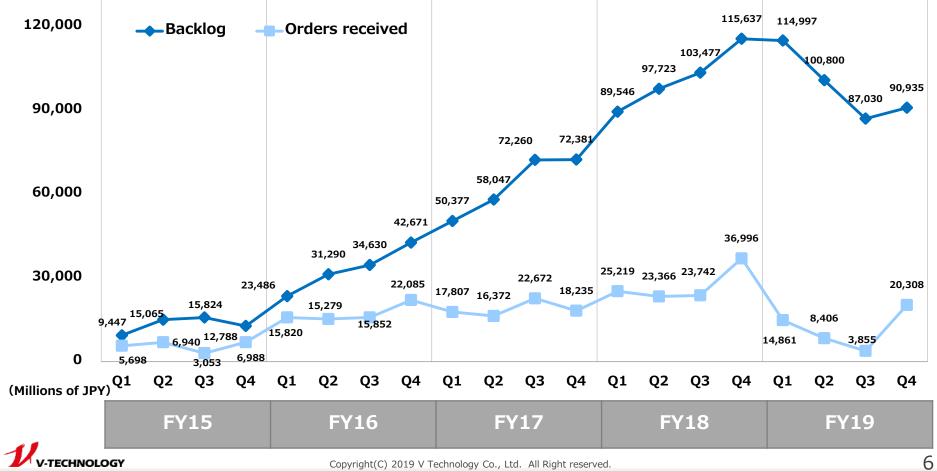




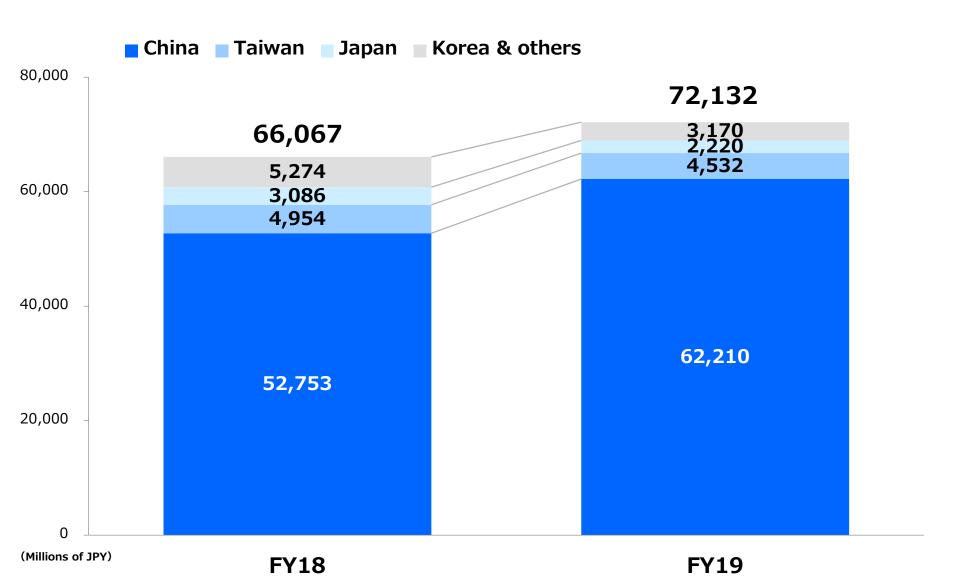


Transition of Orders Received and Backlog

- Orders received for FY19 Q4 (3 months) recovered as expected.
- Orders received for the full-year decreased 56.6% YoY to 47.4 billion yen due to the reaction to the concentration of orders for long delivery products in the previous year and the suspension of investment related to large FPDs. The order backlog decreased 21.4% YoY to 90.9 billion yen.



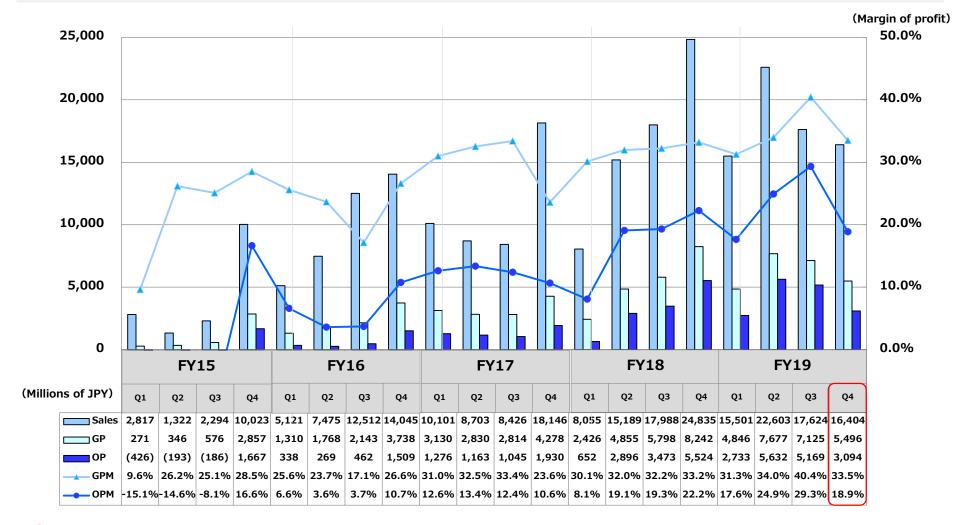
Sales by Countries (YoY basis)





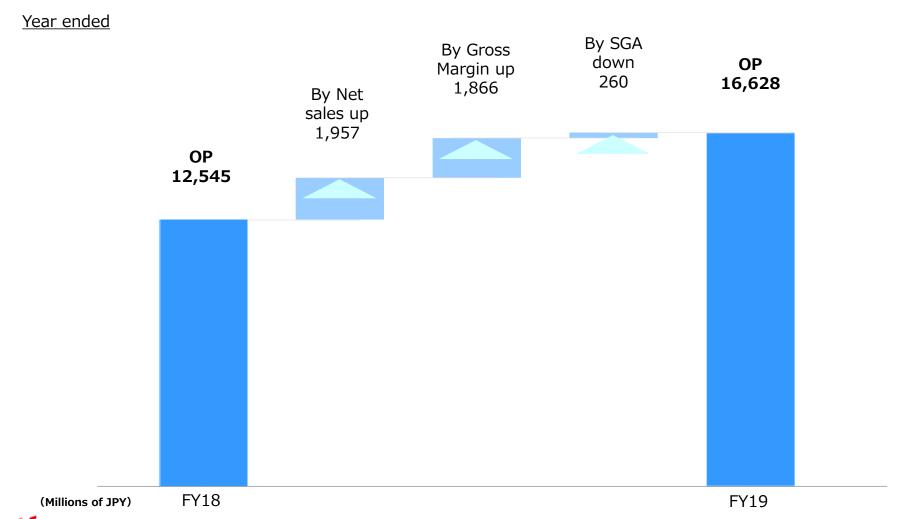
Transition of Quarterly Sales and Profit

 Quarterly profit margin changes due to differences in customers and product mix.



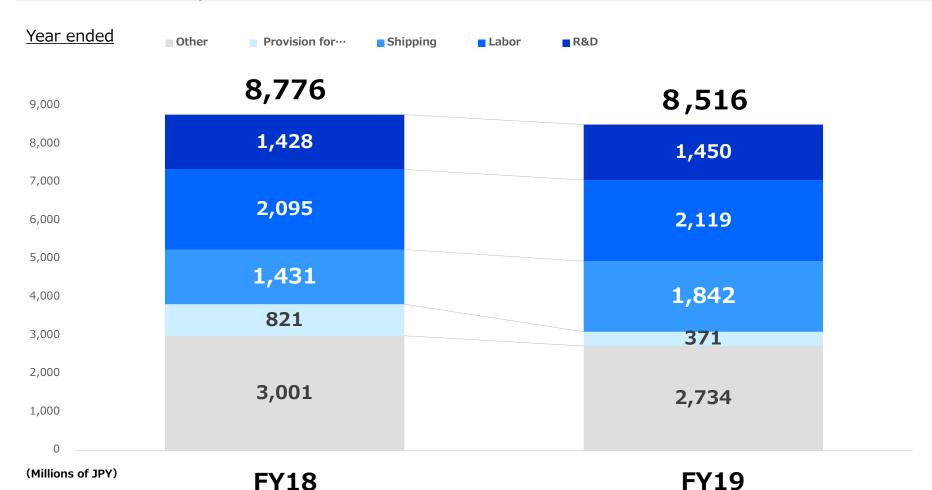
Analysis of Operating Profit Deference

Operating income increased 32.5% YoY to 16.6 billion yen, partly due to cost reductions, improved product mix and lower SG & A expenses as a factor in rising gross margin.

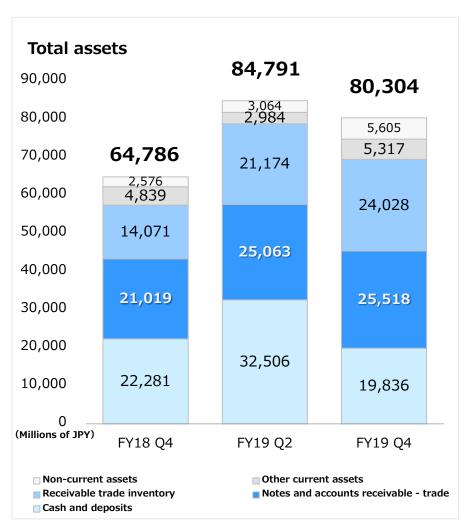


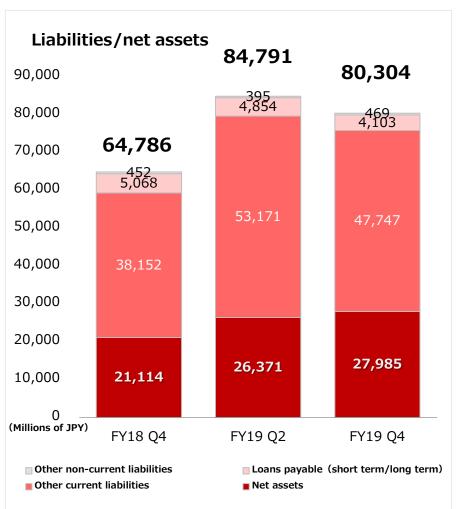
SGA(Selling, general and administrative) Expenses

■ SGA expenses decreased slightly year on year due to an increase in provision for product warranty related to new products in FY 18 and a return of allowance for loan losses at group companies, despite an increase in shipping costs due to increased shipment volume.



Transition of Consolidated Balance Sheets







Transition of Cash Flows

- Main income and expenses (YoY)
 - > Operating activities(+):Profit(JPY16.8BLN), Advances received(7.4BLN),Inventories(9.9BLN) etc.
 - ➤ Investing activities(-):Purchase of fixed assets(*related to VET Co.,Ltd.) (2.1BLN), Purchase of shares of an affiliated company(0.5BLN)
 - ➤ Financing activities(-):Purchase of treasury shares(1.99BLN), Cash dividends paid(1.6BLN),
 Repayments of long-term loans payable (0.9BLN)

		FY18	FY19
	Profit before income taxes	12,256	16,892
	Notes and accounts receivable - trade (increase▲)	▲3,780	▲4,681
Cash flows from operating	Inventories (increase▲)	▲ 5,665	▲9,951
activities	Notes and accounts payable - trade (decrease▲)	7,203	2,044
	Other	▲ 1,488	2,227
	Total	8,526	6,531
Cash flows from inv	vesting activities: Total	▲ 434	▲2,617
	Proceeds from loans payable	8,224	10,670
Cash flows from financing activities	Repayments of loans payable	▲8,876	▲ 11,635
	Other	▲ 1,498	▲ 5,420
	Total	▲2,150	▲ 6,385
Effect of exchange rate change on cash and cash equivalents		▲71	25
Net increase (decrease) in cash and cash equivalents (decrease▲)		5,870	▲2,445
Cash and cash equivalents at beginning of period		16,291	22,161
Cash and cash equivalents at end of period		22,161	19,716



Business Forecast

Forecast of 2020

- Profits are expected to decrease by about 21% due to the decrease in gross margin rate due to the change in sales composition of manufacturing equipment and the increase in SGA expenses such as R & D expenses and depreciation expenses (VET Co.,Ltd. related).
- The dividend is expected to be the same as the previous year.
- Stock split (Split into two, record date: June 1, 2019)

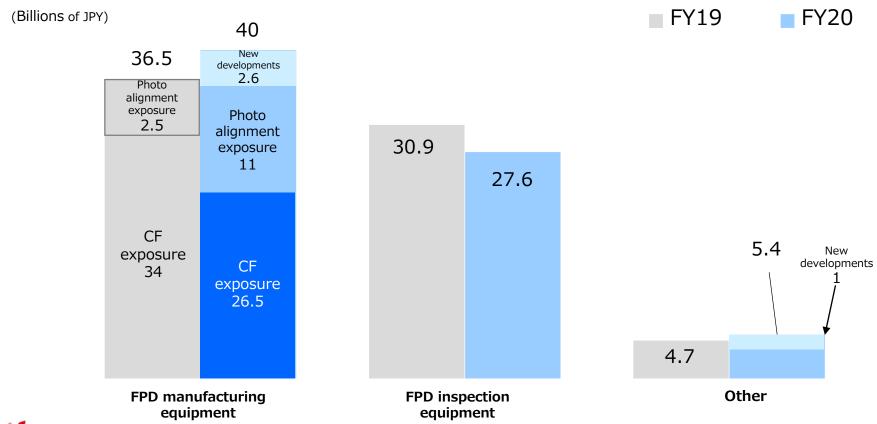
	FY19(A	ctual)	FY20(Fo	compared with the previous	
	Amount (Millions of JPY)	Margin	Amount (Millions of JPY)	Margin	forecast
Net sales	72,132	-	73,000	_	1.2%
Gross profit	16,628	23.1%	13,000	17.8%	-21.8%
Ordinary profit	16,767	23.2%	12,850	17.6%	-23.4%
Net profit attributable to owners of parent	10,901	15.1%	7,800	10.7%	-28.5%
EPS	JPY 2,217.48		JPY 1,613.30(before split) JPY 806.65(after split)		Split into two from June 1,2019

Dividend

FY20(after stock split)	1 st half:80円(Forecast)	2 nd half: JPY 80 (forecast)
(Reference) FY19	1st half: JPY 160 (Actual)	2 nd half: JPY 160 (Actual)

*Reference: Break Down of Net sales in FY2020 Forecast

- Among manufacturing equipment, the proportion of photo alignment exposure equipment increased, and the gross profit rate of manufacturing equipment decreased YoY.
- New developments includes TFT exposure equipment (JPY 2.6 Billion) in "Manufacturing equipment", and deposition mask and salvage service (JPY 1 Billion) in "Other".



1/V-TECHNOLOGY

Our Medium and Long Term Growth Strategy



Growing Field in the New Era



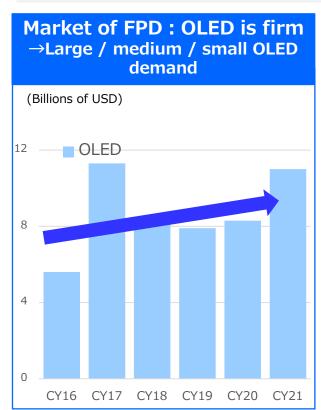
5GEnables the New Era of IoT

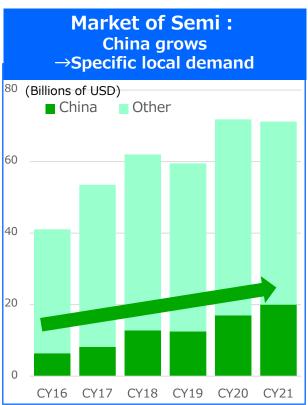
Semiconductors and next-generation human interface (HM) have endless possibilities.

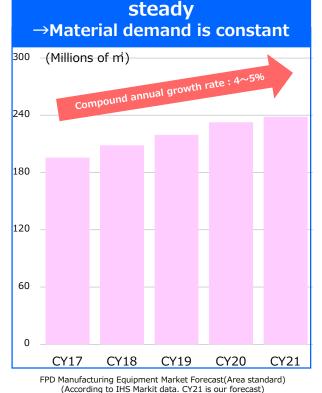


Aiming for the World's Leading Manufacturing Solution Provider

- Accelerate entry into growing fields
 - 1. Endeavor to explore the market of FPD (OLED: Foldable/Rollable/Wearable/8K,LCD:8K)
 - 2. Entry into different fields (semiconductors)
 - 3. Shift the center of business from equipment to parts, materials and services







Market of FPD(area):

Semicnductor Manufacturing Equipment Market Forecast

FPD Manufacturing Equipment Market Forecast (According to IHS Markit data. CY21 is our forecast) (According to SEMI data. CY21 is our forecast)

ECHNOLOGY

1. Endeavor to Explore the Market of FPD (1/6)

■ Rollable TV, Foldable Phone, Wearable device are expected to evolve as nextgeneration display device, however, it has challenges in spreading.

Large 種類		Medium / Small					
1	TV		Smartphone		Wearable		
Next- generation technologies	WOLED		OLED		µLED (UV light conversion type)		
Application	Rollable TV		Foldable Phone		Wearable device		
Important Process and Related Technologies / Materials	TFT Oxide PLAS	Deposition Horizontal deposition, Organic material	TFT LTPS	Deposition Vertical deposition, Organic material, Deposition mask	Module	LED lift off Lift off technology	LED transfer High efficiency transfer

1. Endeavor to Explore the Market of FPD (2/6) Large FPD for TV

<Front-runner of large FPD is WOLED>

Challenges

- Characteristic improvement of TFT (electron mobility)
 - ➤ Approach 1: OxideTFT (issues of yield)
 - ➤ Approach 2: LTPS-TFT (cost and crystal homogeneity)
 - ✓ Next-generation laser annealing technology (LTPS-Like technology development)
- Deposition equipment (Page 22)
- WOLED material cost (made Flask as a subsidiary)



Materials for OLED (FLASK)



(Website of FLASK)

Strengths

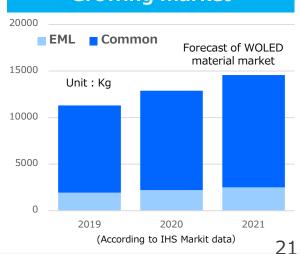
- Technology development ability to synthesize materials according to customer requirements
- state-of-the-art material technologies
- Experts of organic material synthesis

[Key items]

- 1. Material development for WOLED.
- 2. Commercialization of low cost, high luminous efficiency organic EL lighting materials.



Growing market



1. Endeavor to Explore the Market of FPD (3/6) Medium/Small FPD for Smartphone

< Small and medium OLEDs are evolving by deposition >

Challenges

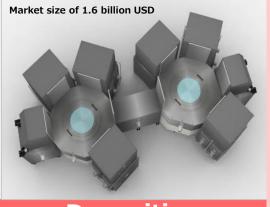
- Process of deposition
 - > Size reduction of deposition equipment, G6 full size compatible
 - Deposition mask
 - OLED material cost
- Process of TFT
 - ightharpoonup Crystal shape of LTPS ightharpoonup Large impact on flexible substrate
 - ✓ (LTPS-Like technology development)



Salvage service



Laser annealing equipment



Deposition equipment

■ Small and medium FPD

- Vertical deposition
- > G6 full size compatible
- Our demonstration equipment is scheduled to be completed in the current fiscal year

■ Large FPD

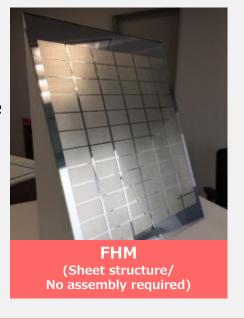
- Development of a deposition equipment that can be also used as a deposition equipment for organic EL lighting
- Technologies from Lumiotec and Flask

1. Endeavor to Explore the Market of FPD (4/6) Medium/Small FPD for Smartphone

 \leq Small and medium OLEDs are evolving by deposition \geq

Challenges

- Process of deposition
 - > Size reduction of deposition equipment, G6 full size compatible
 - Deposition mask
 - OLED material cost
- Process of TFT
 - ➤ Crystal shape of LTPS → Large impact on flexible substrate
 - √ (Technology development of LTPS-Like)
- Process of module
 - Salvage service

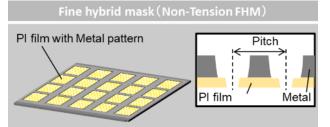


Fine Hybrid Mask



- Established a production line in Yonezawa, one of the base of OLED industry area in Japan.
- Scheduled to start shipping in November

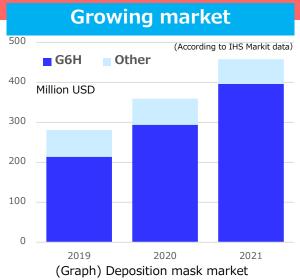
Excellent performance



- (1) PI film with metal pattern (5 μm t)
- (2) Non-Tension FHM(3~7kg/G6H)
- (1)Resolution of Pattern∶ Over 700 ppi (2)Pattern PitchAccuracy: ±2 μm

(Table) FHM structure and specifications

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1. Endeavor to Explore the Market of FPD (5/6) Medium/Small FPD for Smartphone

 \leq Small and medium OLEDs are evolving by deposition \geq

Challenges

- Process of deposition
 - > Size reduction of deposition equipment, G6 full size compatible
 - Deposition mask
 - > OLED material cost
- Process of TFT

Crystal shape of LTPS → Large impact on flexible substrate

✓ (Technology development of LTPS-Like)

- Process of module
 - Salvage service



Image of OLED unevenness defect

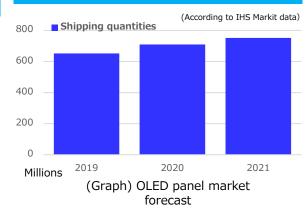
Salvage service

- Scheduled to start within current fiscal year
- Fix panel mura defective with "Demura" technologies while maintaining the brightness and γ characteristics

Immediate improvement of yield in module process

- Doubling yield improvement in module process
- Pay per-use services according to the number of non-defective panels
- MAX60 K / month processing possible with 6 inch panel with 1 salvage line

Stable market (CAGR9%)



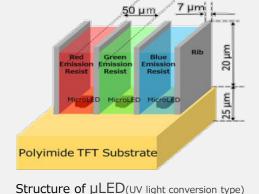


1. Endeavor to explore the market of FPD (6/6) Medium/Small FPD for Wearable device

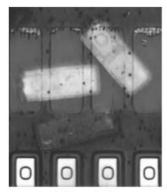
⟨Front-runner of small and medium FPD is µLED(UV light conversion type)⟩

Challenges

- Pick&Place
 - Misalignment during picking up the LED chip LED chip Misalignment during LLO (Fig4.1)
 - Misalignment during LED chip crimping



μLED



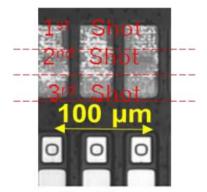


Fig. 4.1 Fig. 4.2 Fig. 4 Chips lifted off with 2000mJ/cm²

The chip in Fig. 4.1 was shot on the size of the chip. The chip in Fig. 4.2 was shot on 1/3 the chip size

- LED laser is locally irradiated by 1/3 each of the chip to prevent misalignment.(Fig4.1/4.2)
- Our proprietary technologies (AEGIS) technology using micro lens array technology and image processing) made it possible of local LLO "PS-LLO"

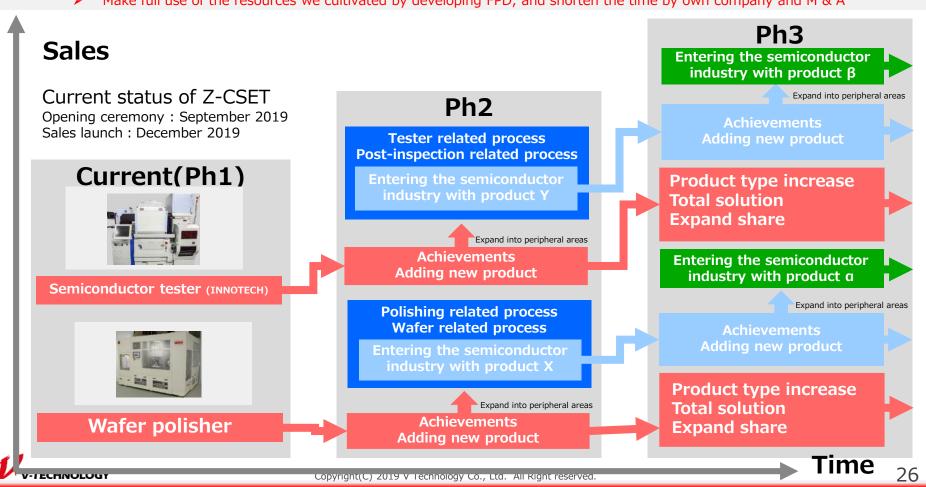
*Reference: Presentation of IDW2018



2. Entry into different fields (semiconductors)

<Current activities and future outlook>

- We will expand into peripheral areas starting from the Z-CSET business.(Highlighted in pink boxes)
- Main constituents of the deployment are VT alone, Z-CSET, and collaboration with other companies.
- We aim to provide a total solution in the semiconductor manufacturing field in the medium to long term.
 - Make full use of the resources we cultivated by developing FPD, and shorten the time by own company and M & A



3. Shift the center of business from equipment to parts, materials and services

1. Materials

A. FPD: Made FLASK corporation as a subsidiary (Page21)

B. SEMI: Our subsidiary and Chinese sales company "VETON" is in charge of material agent sales activities.

2. Parts

Fine Hybrid Mask (FHM)

3. Services

A.Service related equipment (A/S, remodeling, consumable parts)

- B. Temporary staffing service
- C. Salvage service



Providing high-tech staffing business in China

(Expert engineers can be dispatched also in Japan)

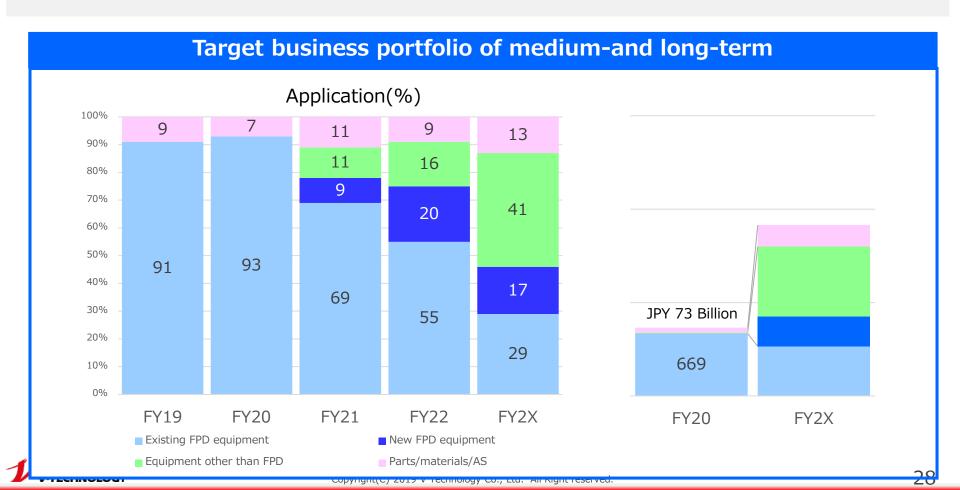
We are considering of new business based on knowledge and network cultivated by FPD device development

- 微鉄克(上海)人力資源管理有限公司
 - (V-Technology (Shanghai) Human Resource Management Co.,Ltd.)
 - > Labor dispatch, human resource consultant, human resource introduction, technical consulting, technical service, corporate management consulting, interpreting service, marketing sales planning, etc.



Aiming for the World's Leading Manufacturing Solution Provider (Summary)

- Accelerate entry into growing fields and aim to achieve business diversification and stable growth.
 - 1. Endeavor to explore the market of FPD
 - 2. Entry into different fields (semiconductors)
 - 3. Shift the center of business from equipment to parts, materials and services





*Reference: Overview of FLASK corporation

Main business activities

Research and development and manufacturing and sales in the fields of organic semiconductor materials such as organic EL materials, inorganic semiconductor materials for organic EL, and organic / inorganic hybrid materials, etc.

Strengths

- -Technology development ability to synthesize materials according to customer requirements
- -state-of-the-art material technologies
- -Experts of organic material synthesis

Head office	Frontier Center for Organic Materials 6F, 4-3-16 Jonan, Yonezawa, Yamagata 992-8510 Japan	
Capital	JPY 45 Million	
Shareholders V Technology Co.,Ltd.(80%) Other(20%)		
President and CEO	Takuya Komoda	
Director	Yukihiro Kanzawa	

